

AN IMPROVED THERMAL MODULE

ABSTRACT

5 The present invention is in related to an improved thermal module, comprising a heat-absorbing portion, a heat-transmitting portion and a heat-conducting portion, a fixing structure fastening the three portions. The heat-absorbing portion absorbs heat generated by a heating element as a chip firstly, and the absorbed heat is then delivered to the heat-conducting portion by means of the heat-transmitting portion for radiation of heat due to a wide surface of the heat-
10 conducting portion. The fixing structure has a piece of flexible member and plural joining elements, the flexible member covers on the heat-absorbing portion as well. An outer rim of the flexible member defines a fastening structure to cooperate with the joining elements for fixing the heat-absorbing portion.